

; YbYfU` 8YgWf]dh]cb`

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® Z series is integrated with fast recovery diode (FRD) to minimize reverse recovery time. It is suitable for resonant switching topologies to reach higher efficiency, higher reliability and smaller form factor.

: YUh i fYg`

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Ultra-fast and robust body diode

5dd`]WUh]cbg`

- PC power
- Telecom power
- Server power
- EV Charger
- Motor driver



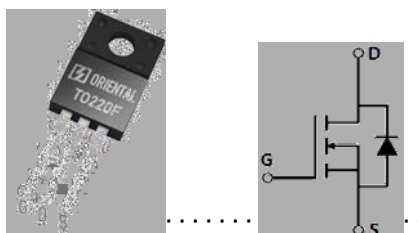
?Ym`DYfZcf a UbWY`DUfU a YhYfg` . . .`

DUfU a YhYf`	JU` i Y`	I b]h`
$V_{DS, min} @ T_{j(max)}$	600	V
$I_D, pulse$	141	A
$R_{DS(ON), max} @ V_{GS}=10V$	74	m
Q_g	44.8	nC

AUf_]b [`=bZcf a Uh]cb`

DfcX i Wh`BU a Y`	DUW_U[Y`	AUf_]b [`
OSG55R074FZF	TO220F	OSG55R074FZ

DUW_U[Y` / `D]b`=bZcf a Uh]cb`



5Vgc`ihY`AUI]a ia`FUh]b]g at $T_j=25^\circ\text{C}$ unless otherwise noted

DUfU a YhYf`	Gma Vc`	JU`iY`	I b]h`
Drain-source voltage	V_{DS}	550	V
Gate-source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	47	A
Continuous drain current ¹⁾ , $T_C=100^\circ\text{C}$		30	
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D, pulse}$	141	A
Continuous diode forward current ¹⁾ , $T_C=25^\circ\text{C}$	I_S	47	A
Diode pulsed current ²⁾ , $T_C=25^\circ\text{C}$	$I_{S, pulse}$	141	A
Power dissipation ³⁾ , $T_C=25^\circ\text{C}$	P_D	35	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	1000	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\dots 480\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\dots 480\text{ V}$, $I_{SD} = I_D$	dv/dt	50	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^\circ\text{C}$

H\Yf a U`7 \UfUWhYf]gh]Wg`

DUfU a YhYf`	Gma Vc`	JU`iY`	I b]h`
Thermal resistance, junction-case	R_{JC}	3.6	$^\circ\text{C/W}$
Thermal resistance, junction-ambient ⁴⁾	R_{JA}	62.5	$^\circ\text{C/W}$

9`YWhf]WU`7 \UfUWhYf]gh]Wg` at $T_j=25^\circ\text{C}$ unless otherwise specified

DUfU a YhYf`	Gma Vc`	A]b`	Hmd`	AUI`	I b]h`	HYgh`WcbX]h]cb`
Drain-source breakdown voltage	BV_{DSS}	550			V	$V_{GS}=0\text{ V}$, $I_D=1\text{ mA}$
		600				$V_{GS}=0\text{ V}$, $I_D=1\text{ mA}$, $T_j=150^\circ\text{C}$
Gate threshold voltage	$V_{GS(th)}$	3.5		4.5	V	$V_{DS}=V_{GS}$, $I_D=1\text{ mA}$
Drain-source on-state resistance	$R_{DS(ON)}$		0.066	0.074		$V_{GS}=10\text{ V}$, $I_D=23.5\text{ A}$
			0.16			$V_{GS}=10\text{ V}$, $I_D=23.5\text{ A}$, $T_j=150^\circ\text{C}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=30\text{ V}$
				-100		$V_{GS}=-30\text{ V}$
Drain-source leakage current	I_{DSS}			10	μA	$V_{DS}=600\text{ V}$, $V_{GS}=0\text{ V}$
Gate resistance	R_G		8			$f=1\text{ MHz}$ Open drain

8mbU a]W' 7 \UfUWhYf]gh]Wg'

DUFU a YhYf'	Gm a Vc''	A]b''	Hmd''	AUI''	I b]h'	HYgh'WcbX]h]cb
Input capacitance	C _{iss}		2933		pF	V _{GS} =0 V, V _{DS} =50 V, f=100 KHz
Output capacitance	C _{oss}		350.1		pF	
Reverse transfer capacitance	C _{rss}		7.04		pF	
Turn-on delay time	t _{d(on)}		92.3		ns	V _{GS} =10 V, V _{DS} =400 V, R _G =2 , I _D =25 A
Rise time	t _r		98.1		ns	
Turn-off delay time	t _{d(off)}		75.5		ns	
Fall time	t _f		63.9		ns	

; UhY' 7 \Uf [Y' 7 \UfUWhYf]gh]Wg'

DUFU a YhYf'	Gm a Vc''	A]b''	Hmd''	AUI''	I b]h'	HYgh'WcbX]h]cb
Total gate charge	Q _g		44.8		nC	V _{GS} =10 V, V _{DS} =400 V, I _D =25 A
Gate-source charge	Q _{gs}		18.2		nC	
Gate-drain charge	Q _{gd}		13.8		nC	
Gate plateau voltage	V _{plateau}		5.6		V	

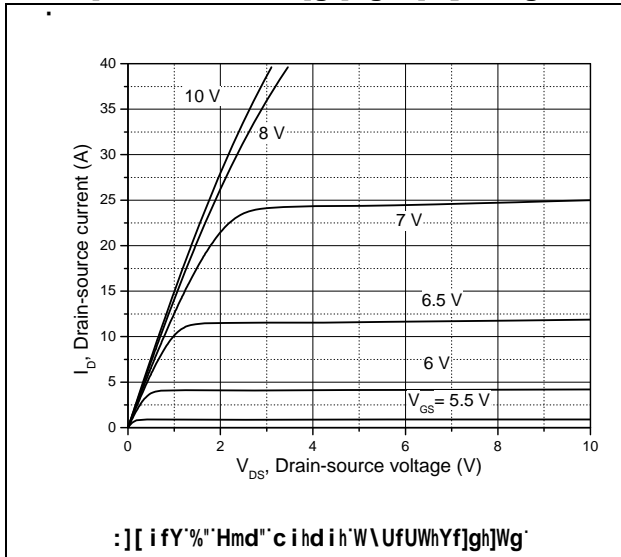
6cXm' 8]cXY' 7 \UfUWhYf]gh]Wg'

DUFU a YhYf'	Gm a Vc''	A]b''	Hmd''	AUI''	I b]h'	HYgh'WcbX]h]cb
Diode forward voltage	V _{SD}			1.4	V	I _S =47 A, V _{GS} =0 V
Reverse recovery time	t _{rr}		167		ns	I _S =25 A, di/dt=100 A/μs
Reverse recovery charge	Q _{rr}		1.1		uC	
Peak reverse recovery current	I _{rrm}		12.7		A	

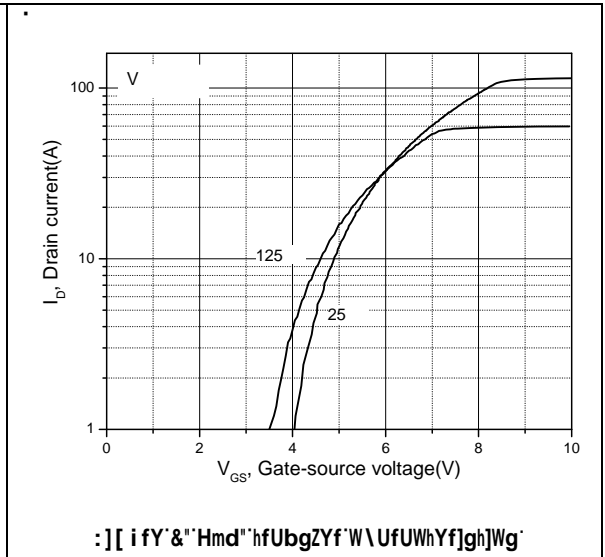
BchY'

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{JA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=100 V, V_{GS}=10 V, L=60 mH, starting T_j=25 °C.

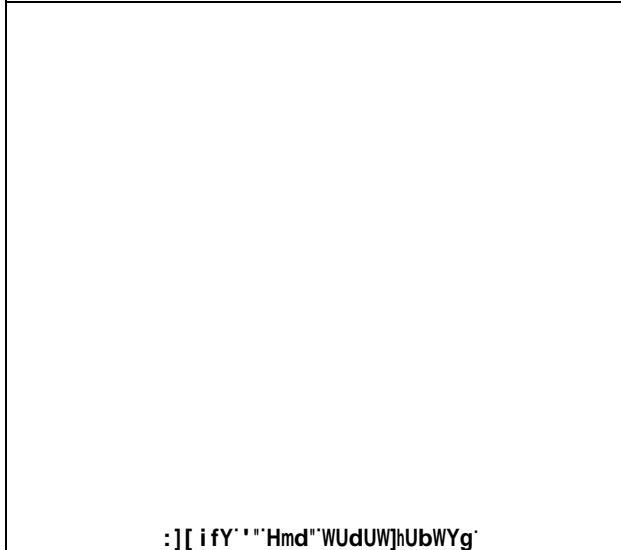
9`YWhf]WU`7 \UfUWhYf]gh]Wg`8]U[fUag`



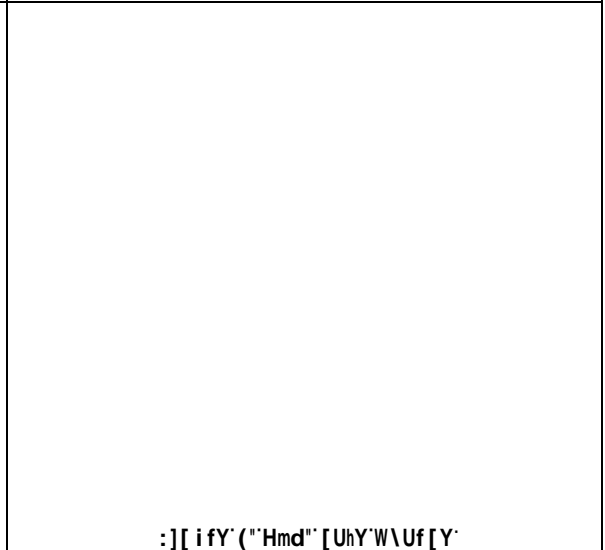
:][i fY`%"`Hmd" c i h d i h`W \UfUWhYf]gh]Wg`



:][i fY`&"`Hmd" hfUbgZYf`W \UfUWhYf]gh]Wg`



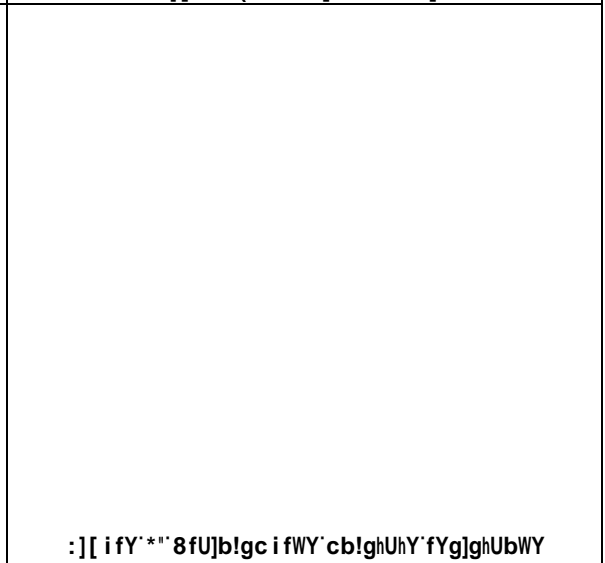
:][i fY`""`Hmd" WUdUW]hUbWYg`



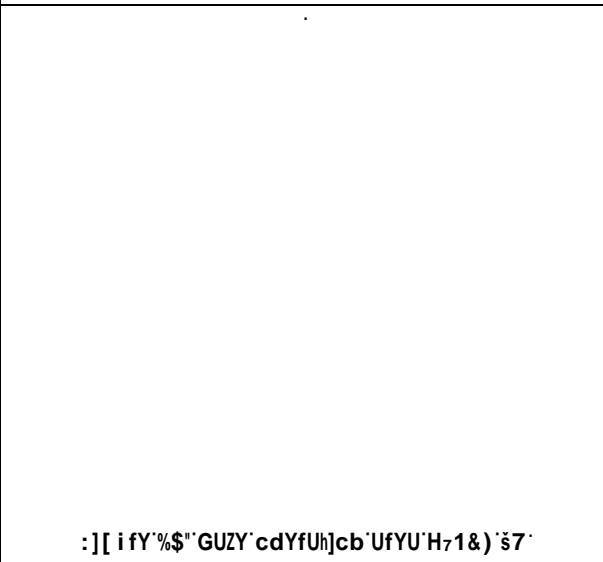
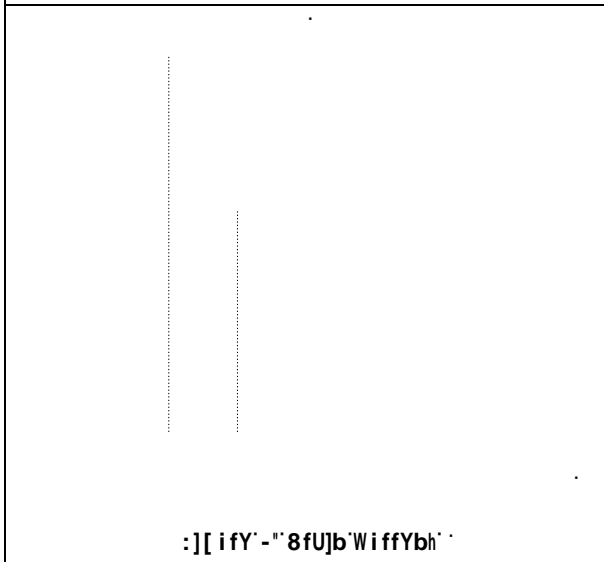
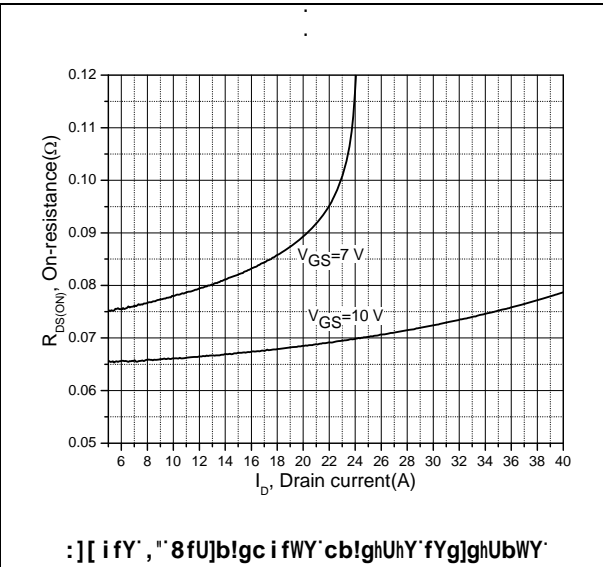
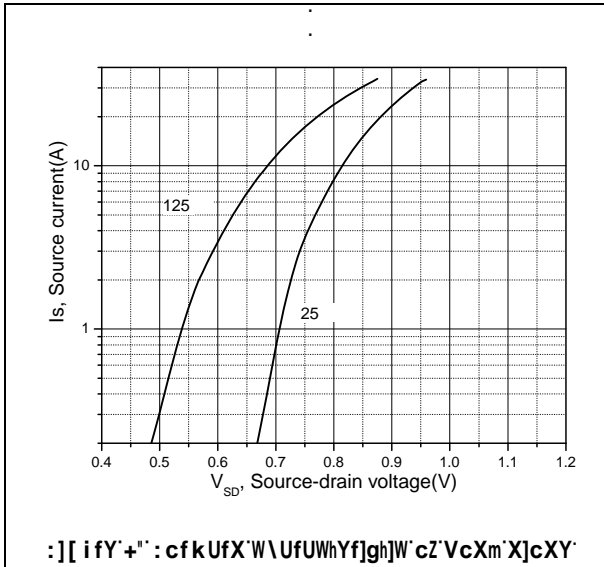
:][i fY`("`Hmd" [UhY`W \Uf [Y`



:][i fY`)"`8fU]b!gc i fWY`VfYU_Xc kb` jc`hU [Y`



:][i fY`*"`8fU]b!gc i fWY` cb!ghUhY`fYg]ghUbWY`



HYgh'Wjfw i]hg'UbX' kUjYZcf ag'

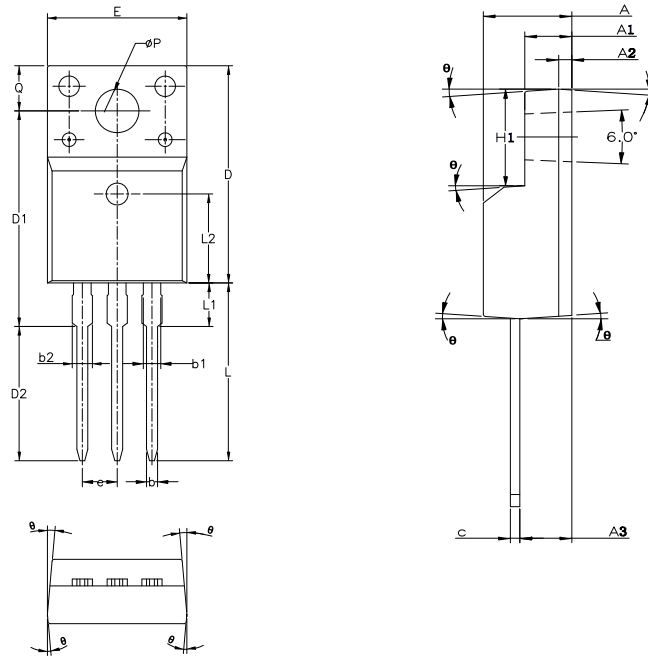


DUW_U [Y' =bZcf a Uh]cb

Symbol	mm		
	Min	Nom	Max
E	9.96	10.16	10.36
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A4	2.56	2.76	2.96
c	0.40	0.50	0.65
D	15.57	15.87	16.17
H1	6.70 REF		
e	2.54 BSC		
L	12.68	12.98	13.28
L1	2.88	3.03	3.18
P	3.03	3.18	3.38
P3	3.15	3.45	3.65
F3	3.15	3.30	3.45
G3	1.25	1.35	1.55
b1	1.18	1.28	1.43
b2	0.70	0.80	0.95

Version 1: TO220F-C outline dimension

DUW_U [Y' = bZcf a Uh]cb



Symbol	mm		
	Min	Nom	Max
A	4.50	4.70	4.83
A1	2.34	2.54	2.74
A2	0.70 REF		
A3	2.56	2.76	2.93
b	0.70	-	0.90
b1	1.18	-	1.38
b2	-	-	1.47
c	0.45	0.50	0.60
D	15.67	15.87	16.07
D1	15.55	15.75	15.95
D2	9.60	9.80	10.00
E	9.96	10.16	10.36
e	2.54 BSC		
H1	6.48	6.68	6.88
L	12.68	12.98	13.28
L1	-	-	3.50
L2	6.50 REF		
P	3.08	3.18	3.28
Q	3.20	-	3.40
	1°	3°	5°

Version 2: TO220F-J outline dimension

CfXYf]b [:bZcf a Uh]cb`

DUW_U[Y` HmdY`	I b]hg#` Hi VY`	Hi VYg`#` :bbYf`6 c l`	I b]hg#` :bbYf`6 c l`	:bbYf`6 c lYg#` 7Ufhcb`6 c l`	I b]hg#` 7Ufhcb`6 c l`
TO220F-C	50	20	1000	6	6000
TO220F-J	50	20	1000	5	5000

DfcX i Wh :bZcf a Uh]cb`

DfcX i Wh`	DUW_U[Y`	DV` :fYY`	Fc<G`	<U`c [Yb` :fYY`
OSG55R074FZF	TO220F	yes	yes	yes

@Y [U` 8]gW`U] a Yf`

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¥`Cf]YbhU`GY a]WcbX i Whcf`7 c"z@hX"5`F][\hg`FYgYf jYX`